

Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

06 162 FR4 35 L20.35 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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| Layers | in μ | Material | Build-Up | Assembly |
|----------|-----------|----------|--|--|
| Layer-1 | 35 μ | Copper |  |  |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg |  | |
| Layer-2 | 35 μ | Copper | | |
| | 200 μ | L-FR4 |  | |
| Layer-3 | 35 μ | Copper | | |
| | 180 μ | Prepreg |  | |
| | 180 μ | Prepreg | | |
| Layer-4 | 35 μ | Copper |  | |
| | 200 μ | L-FR4 | | |
| Layer-5 | 35 μ | Copper |  | |
| | 180 μ | Prepreg | |  |
| | 180 μ | Prepreg |  | |
| Layer-99 | 35 μ | Copper | |  |

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